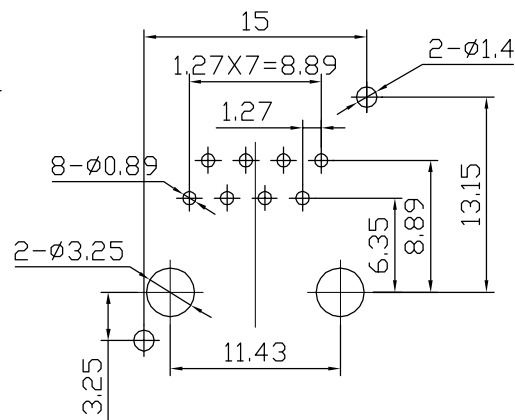
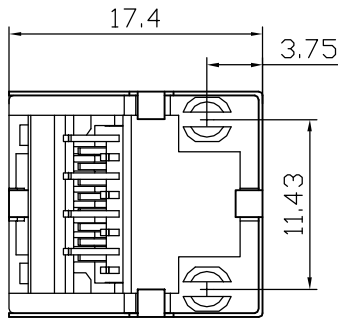
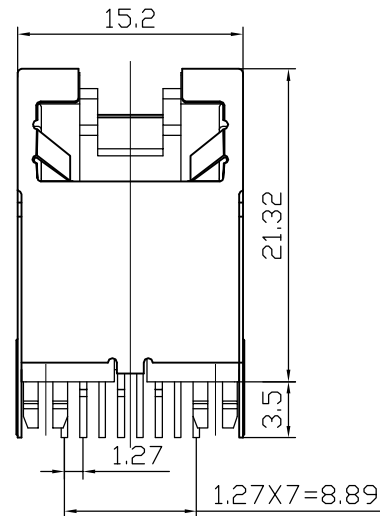
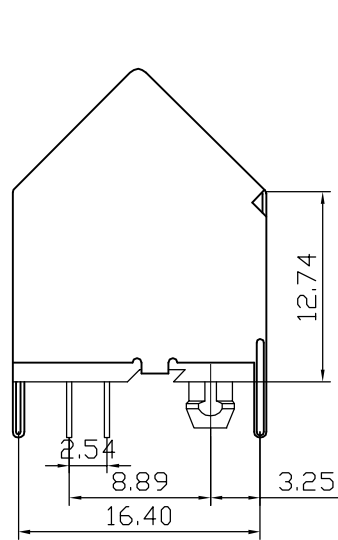


REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	CHKD



PC Board Layout  
Component Side Shown

NOTES:

MATERIAL:

- HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE t=0.30mm.
- PLATING : SELECTING GOLD PLATING 3u"~50u" OVER NICKEL IN CONTACT AREA. 150u" TIN PLATING OVER NICKEL IN SOLDER AREA
- SHIELD : 0.20mm THICKNESS COPPER ALLOY WITH NICKEL PLATED.

ELECTRICAL:

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 30 MILLIOHMS MAX.
- INSULATION RESISTANCE : 500 MEGOHMS MIN @ 500V DC .
- DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- DURRABILITY : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.

ENVIRONMENTAL:

- STORAGE : -40° C TO 85° C.
- OPERATION : 0° C TO 70° C.

DETACHED LISTS	← MM (INCH) →		DFTO: SHB	DATE: 2007.10.05	<h1>Coorle 库乐科技</h1>
	TOLERANCES EXCEPT AS NOTED		CHKD: LANBO	DATE: 2007.10.05	
	MM	±	MFO:	DATE:	
	.0 ± 0.15	±	APPLV:	DATE:	
			MATERIAL :		TITLE
			ANGLES ± 0.5		5226 8P8CS 45°
			THIRD ANGLE PROJECTION		QT'Y :
			FINISH :		DRAWING NO.
			SCALE :		/PART NO.
			DO NOT SCALE DRAWING		SIZE REV
			SHEET		A3 0
			OF		